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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10024154	12/18/2001	257		2826	GREENE, P

**APPLICANTS: Ohno Tsuyoshi;

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CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
JAPAN 2000-389519 12/21/2000

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no			NEKW.19.286
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no			
Verified and Acknowledged Examiners's initials			
TITLE : Flip chip semiconductor device having signal pads arranged outside of power supply pads			

U.S. DEPT. OF COMM/PAT & TM-PTO-435L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED			
			Total Claims	Print Claim for O.G		
ISSUE FEE		Primary Examiner	DRAWING			
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner			
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